

PCN Number:	20170724000	PCN Date:	August 4, 2017
Title:	Datasheet for DS90UH926Q-Q1, DS90UB926Q-Q1, DS90UH302Q-Q1, and DS90UB302Q-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



DS90UH926Q-Q1

SNLS337M – OCTOBER 2010 – REVISED AUGUST 2017

Changes from Revision L (February 2017) to Revision M	Page
• Reverted all previous MLCK content changes made in Revision L back to Revision K	1
• Removed disable jitter cleaner note	5

Changes from Revision K (January 2015) to Revision L	Page
• Changed top view pin out diagram	4
• Changed CLK to RES2	5
• Added note to disable jitter cleaner	5
• Changed MCLK to RES2	5
• Deleted reference to MCLK in this section	8
• Deleted reference to MCLK in this section	11
• Deleted reference to MCLK	25
• Deleted <i>I2S Jitter Cleaning</i> section	25
• Deleted <i>MCLK</i> section	25
• Deleted MCLK columns in the <i>Audio Interface Frequencies</i> table	26
• Changed values in columns 2 to 5 of Configuration Select (MODE_SEL) table	29
• Changed values in columns 2 to 5 of IDx table	32
• Changed Removed register reference to MCLK	42
• Changed Typical Display System Diagram (removed MCLK)	47
• Changed Power-Up Requirements and PDB pin description and added Power-Up Sequence graphic.	50

Changes from Revision C (February 2017) to Revision D **Page**

• Reverted all previous MCLK content changes made in Revision C back to Revision B.....	1
• Deleted the disable I2S jitter cleaner note.....	5

Changes from Revision B (January 2015) to Revision C **Page**

• Changed pin 60 from MCLK to RES2	4
• Changed MCLK to RES2	5
• Added note to disable I2S jitter cleaner	5
• Changed MCLK to RES2	5
• Deleted reference to MCLK in this section	8
• Deleted reference to MCLK in this section	12
• Deleted reference to MCLK.....	27
• Changed <i>MCLK</i> section	27
• Changed MCLK columns of <i>Audio Interface Frequencies</i> table	27
• Changed the values in columns 2 through 5 in Configuration Select (MODE_SEL) table.....	31
• Changed the values in columns 2 to 5 in Serial Control Bus Addresses for IDx table	34
• Changed register reference to MCLK	44
• Changed Typical Display System Diagram (removed reference to MCLK)	48
• Changed wording of <i>Power Up Requirements and PDB Pin</i> subsection and added Power-Up Sequence graphic.....	50

Changes from Revision A (April 2013) to Revision B **Page**

• Changed HBM ESD classification level from: ±8 kv to: 3B	1
• Deleted Product Preview marking	1
• Added <i>Device Information</i> and <i>Pin Configuration and Functions</i> sections, <i>ESD Ratings</i> and <i>Thermal Information</i> tables, <i>Feature Description</i> , <i>Device Functional Modes</i> , <i>Application and Implementation</i> , <i>Power Supply Recommendations</i> , <i>Layout, Device and Documentation Support</i> , and <i>Mechanical, Packaging, and Orderable Information</i> sections.....	1
• Deleted sentence "EMI is minimized by the use of low voltage differential signaling, data scrambling and randomization and spread-spectrum clocking compatibility."	1
• Changed the number of column 2 to 5 in Configuration Select (MODE_SEL) table.	25
• Revised the number of column 2 to 5 in IDx table.	28
• Changed "Power Up Requirements and PDB Pin" description and added a power-up sequence diagram.	43
• Added <i>Community Resources</i> section	47

Changes from Revision B (July 2015) to Revision C **Page**

• Added correct automotive bullets	1
• Changed the numbers at column 2 to 5 in Configuration Select (MODE_SEL) table.	26
• Changed the numbers at column 2 to 5 in IDx table	29
• Changed LLP to WQFN	45
• Added <i>Community Resources</i> section	47

The datasheet number will be changing.

Device Family	Change From:	Change To:
DS90UH926Q-Q1	SNLS337K	SNLS337M
DS90UB926Q-Q1	SNLS422B	SNLS422D
DS90UH302Q-Q1	SNLS425A	SNLS425B
DS90UB302Q-Q1	SNLS410B	SNLS410C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DS90UH926Q-Q1>

<http://www.ti.com/product/DS90UB926Q-Q1>

DS90UH302Q-Q1 and DS90UB302Q-Q1; the document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DS90UH926QSQ/NOPB	DS90UH926QSQE/NOPB	DS90UH926QSQX/NOPB	DS90UB926QSQ/NOPB
DS90UB926QSQE/NOPB	DS90UB926QSQX/NOPB	DS90UB302QSQ/NOPB	DS90UB302QSQE/NOPB
DS90UB302QSQX/NOPB	DS90UH302QSQ/NOPB	DS90UH302QSQE/NOPB	DS90UH302QSQX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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